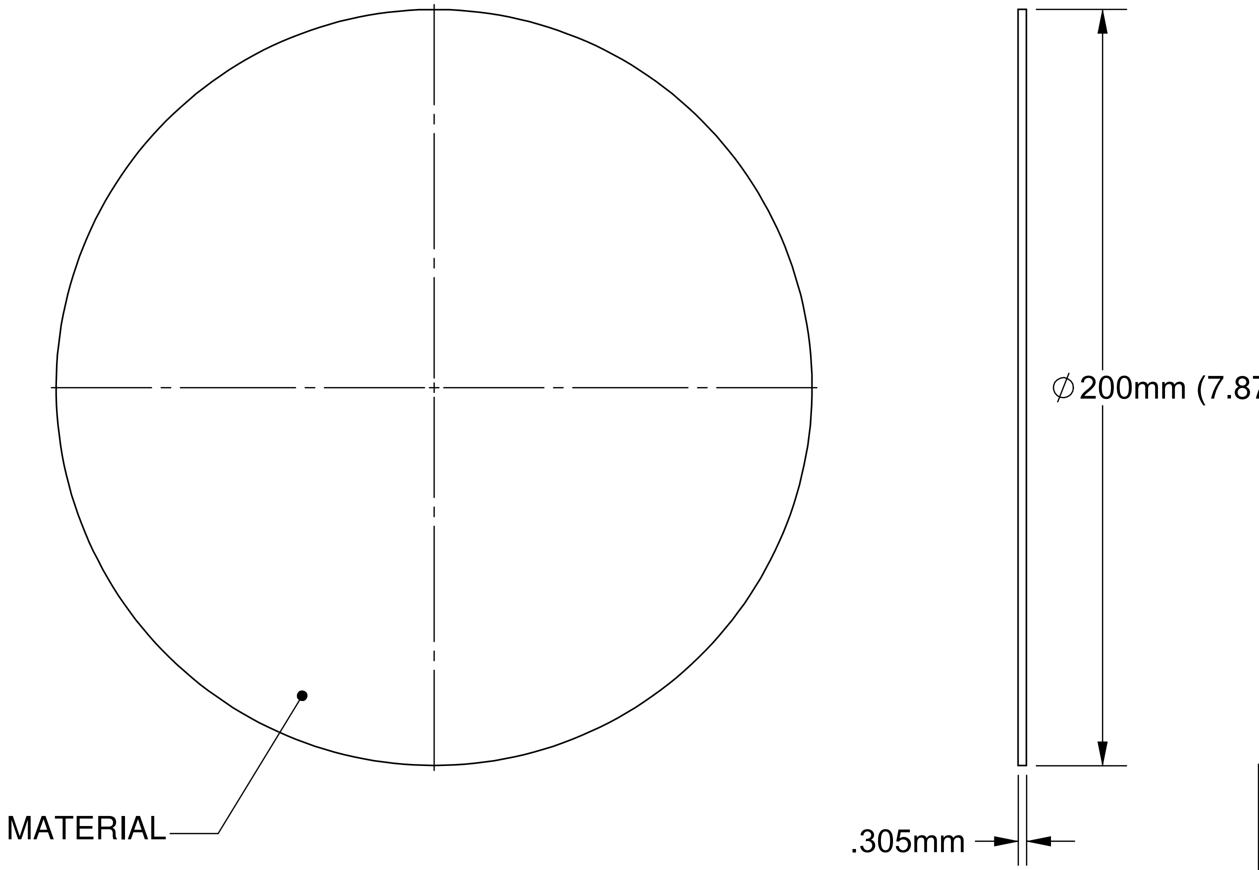

200mm (7.875-inch) UNSAWN WAFER

T THICKNESS ±10%	PART NUMBER	
	288943	288103
0.305mm (0.012")	RO4003C WHITE CERAMIC	HL832NS BLACK PLASTIC

Notes: (Unless Otherwise Specified).
1) ADHESIVE MATERIAL: Thixotropic Latent Cure Adhesive
2) DIMENSIONS: mm (INCH)

TOLERANCE UNLESS NOTED	
X.XX	+/- 0.01
X.XXX	+/- 0.005
X.XXXX	+/- 0.0005
ANGLES	+/- 0.5°

ALL DIMENSIONS IN
☒ INCHES ☐ MILLIMETERS

THIRD ANGLE PROJECTION

APPROVALS	DATE
DRAWN J. Hines	12/12/2010
ENG	
MFG	
QA	
CUST	
REVISED	

Mirror Semiconductor

TITLE
FLAT LID WITH ADHESIVE PREFORM
200mm (7.875-INCH) WAFER

SCALE	SIZE	DRAWING NO.	REV
1:2	A	288103 / 288943	A

DO NOT SCALE DRAWING

SHEET 1 OF 5